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\* Copyright (c) 2015-2018 in2H2 inc.

\* System developed for in2H2 inc. by Intermotion Technology, Inc.

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\* Full system RTL, C sources and board design files available at <https://github.com/nearist>

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\* - Stefano Aldrigo, Board Layout Design

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\* We dedicate this project to the memory of Bruce McCormick, an AI pioneer

\* and advocate, a good friend and father.

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LAYER	DEFINITION	DESCRIPTION	THICKNESS (um)	THICKNESS (mils)
coating		GREEN SOLDER M.	12,5	0,492
TOP	SIGNAL	COPPER	35	1,378
substrate		DIELECTRIC FR4	100	3,937
L2	PLANE LAYER - GND	COPPER	16	0,630
substrate		DIELECTRIC FR4	100	3,937
L3	SIGNAL	COPPER	16	0,630
substrate		DIELECTRIC FR4	100	3,937
L4	SIGNAL	COPPER	16	0,630
substrate		DIELECTRIC FR4	100	3,937
L5	PLANE LAYER - GND	COPPER	70	2,756
substrate		DIELECTRIC FR4	100	3,937
L6	PLANE LAYER - PWR1	COPPER	70	2,756
substrate		DIELECTRIC FR4	100	3,937
L7	PLANE LAYER - PWR1	COPPER	70	2,756
substrate		DIELECTRIC FR4	100	3,937
L8	PLANE LAYER - GND	COPPER	70	2,756
substrate		DIELECTRIC FR4	100	3,937
L9	SIGNAL	COPPER	16	0,630
substrate		DIELECTRIC FR4	100	3,937
L10	SIGNAL	COPPER	16	0,630
substrate		DIELECTRIC FR4	100	3,937
L11	PLANE LAYER - GND	COPPER	16	0,630
substrate		DIELECTRIC FR4	100	3,937
BTM	SIGNAL	COPPER	35	1,378
coating		GREEN SOLDER M.	12,5	0,492
Total Thick.			1571	61,850